



## Material Content Data Sheet



<b>Sales Product Name</b>		ITS4200S-SJ-D		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001243198						
<b>Package</b>		PG-DSO-8-24		<b>Weight*</b>		83.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.188	2.63	2.63	26253	26253
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8605	
wire	non noble metal	copper	7440-50-8	29.121	34.94	35.85	349382	358525
	noble metal	gold	7440-57-5	0.453	0.54	0.54	5439	5439
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1167
encapsulation	plastics	epoxy resin	-	4.473	5.37		53663	
	inorganic material	silicondioxide	60676-86-0	44.048	52.83	58.32	528467	583297
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9764	9764
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7801	7801
glue	plastics	epoxy resin	-	0.130	0.16		1561	
	noble metal	silver	7440-22-4	0.613	0.74	0.90	7360	8921
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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